PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data		
1.1 Company	577	STMicroelectronics International N.V
1.2 PCI No.		MMS/15/9469
1.3 Title of PCI		IMPROVED PACKING for all EEPROM in WLCSP
1.4 Product Category		All EEPROM in WLCSP
1.5 Issue date		2015-10-28

2. PCI Team		
2.1 Contact supplier		
2.1.1 Name	MARSHALL DAVE	
2.1.2 Phone		
2.1.3 Email	dave.marshall@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Benoit RODRIGUES	
2.1.2 Marketing Manager	Hubert LEDUC	
2.1.3 Quality Manager	Rita PAVANO	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape,	STATSChipPAC subcontractor

4. Description of change		
	Old	New
4.1 Description	No bubble sheet, no MBB, no desiccant, no humidity indicator, no EPE foam	Adding bubble wrap sheets, Moisture barrier bag, desiccant and humidity indicator, EPE protector foam
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on form by adding the material of the improved packing	

5. Reason / motivation for change		
5.1 Motivation	Will improve resistance to mechanical and environmental stresses during transportation	
5.2 Customer Benefit	QUALITY IMPROVEMENT	

6. Marking of parts / traceability of change	
6.1 Description	N/A

7. Timing / schedule	
7.1 Date of qualification results	2015-10-22
7.2 Intended start of delivery	2015-10-26
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation			
8.1 Description			
8.2 Qualification report and qualification results		Issue Date	

9. Attachments (additional documentations)

9469PpPrdtLst.pdf PCI NEW PACKING all WLCSP.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
2449210	M24128S-FCU6T/T	
2449213	M24C16-DFCU6TP/K	
2449212	M24C32S-FCU6T/T	
2449211	M24C64S-FCU6T/T	

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